



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-01-20
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacopello	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STTH10LCD06CFP	HFUI*N96B12O	A	Z8GA	2017-01-20
Amount	UoM	Unit type	ST ECOPACK Grade	
1900.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
Not Applicable	Not Applicable	Not Applicable		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DIP	4.3-2.77-2	3	Through-hole	
Comment	Package: TO 220 ISOL FULL PACK 0.5 AB			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HFUI*N96B120					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	2.948	mg	supplier	die	Silicon (Si)	7440-21-3		2.773	mg	940638	1459
				supplier	metallization	Aluminium (Al)	7429-90-5		0.115	mg	39009	61
				supplier	metallization	Titanium (Ti)	7440-32-6		0.003	mg	1018	2
				supplier	metallization	Tungsten (W)	7440-33-7		0.004	mg	1357	2
				supplier	metallization	Nickel (Ni)	7440-02-0		0.012	mg	4071	6
				supplier	Passivation	Silicon Oxide	7631-86-9		0.017	mg	5767	9
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	339	1
				supplier	back side metallization	Gold (Au)	7440-57-5		0.004	mg	1357	2
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.019	mg	6445	10
				Leadframe	Copper & its alloys	1020.391	mg	supplier	alloy	Copper (Cu)	7440-50-8	
supplier	alloy	Iron(Fe)	7439-89-6						1.021	mg	1001	537
supplier	alloy	Phosphorus(P)	12185-10-3						0.511	mg	501	269
Soft solder	Solder	1.728	mg	supplier	solder	Tin(Sn)	7440-31-5		0.035	mg	20255	18
				supplier	solder	Silver(Ag)	7440-22-4		0.043	mg	24884	23
				JIG-R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	1.650	mg	954861	868
Bonding wires	Other inorganic materials	26.598	mg	supplier	wire	Aluminum(Al)	84195-93-7		26.598	mg	1000000	13999
				supplier	mold compound	Solid Epoxy Resin	25068-38-6		81.896	mg	100000	43103
				supplier	mold compound	Phenol Resin	29690-82-2		57.327	mg	70000	30172
				supplier	mold compound	Fused Silica	60676-86-0		41.358	mg	50501	21767
				supplier	mold compound	Crystalline Silica	14808-60-7		614.220	mg	750000	323274
Encapsulation	Other Organic Materials	818.960	mg	supplier	mold compound	Carbon Black	1333-86-4		0.410	mg	501	216
				supplier	mold compound	Metal Hydroxide	21645-51-2		23.749	mg	28999	12499
				supplier	solder alloy	Tin (Sn)	7440-31-5		29.375	mg	1000000	15461
Connections coating	Solder	29.375	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		29.375	mg	1000000	15461